

General Description

The AGM308AP combines advanced trenchMOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

This device is ideal for load switch and battery protection applications.

Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

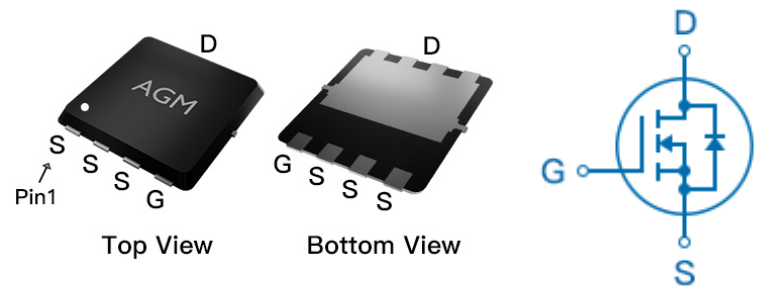
Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Product Summary

BVDSS	RDSON	ID
30V	6.2mΩ	40A

PDFN3.3*3.3 Pin Configuration



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM308AP	AGM308AP	PDFN3.3*3.3	330mm	12mm	5000

Table 1. Absolute Maximum Ratings (TA=25℃)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	30	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25℃) (Note 1)	40	A
	Drain Current-Continuous(Tc=100℃)	24	A
IDM (pluse)	Drain Current-Pulsed (Note 2)	160	A
PD	Maximum Power Dissipation(Tc=25℃)	24	w
	Maximum Power Dissipation(Tc=100℃)	10	w
EAS	Avalanche energy (Note 3)	64	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	℃

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State) ¹	---	50	℃/W
RθJC	Thermal Resistance Junction-Case ¹	---	5.26	℃/W

Table 3. Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250μA	30	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=30V,VGS=0V	--	--	1.0	μA
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V	--	--	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=250μA	1.2	1.6	2.2	V
gFS	Forward Transconductance	VDS=5V,ID=10A	--	15	--	S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=20A	--	6.2	7.5	mΩ
		VGS=4.5V, ID=10A	--	9.0	16	mΩ
Dynamic Characteristics						
Ciss	Input Capacitance	VDS=15V,VGS=0V, F=1MHZ	--	830	--	pF
Coss	Output Capacitance		--	142	--	pF
Crss	Reverse Transfer Capacitance		--	119	--	pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz	--	2.5	--	Ω
Switching Times						
td(on)	Turn-on Delay Time	VGS=10V,VDS=30V, ID=20A,REGEN=3Ω	--	6	--	nS
tr	Turn-on Rise Time		--	5	--	nS
td(off)	Turn-Off Delay Time		--	25	--	nS
tf	Turn-Off Fall Time		--	7	--	nS
Qg	Total Gate Charge	VGS=10V, VDS=15V, ID=20A	--	19	--	nC
Qgs	Gate-Source Charge		--	6.3	--	nC
Qgd	Gate-Drain Charge		--	4.5	--	nC
Source-Drain Diode Characteristics						
ISD	Source-Drain Current(Body Diode)	VG=VD=0V , Force Current	--	--	40	A
VSD	Forward on Voltage	VGS=0V,IS=20A	--	--	1.2	V
trr	Reverse Recovery Time	IF=20A , dI/dt=100A/μs	--	7	--	ns
Qrr	Reverse Recovery Charge	,TJ=25℃	--	6.3	--	nc

Notes 1.The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: TJ=25°C , VDD=20V, Vgs=10V, ID=16A, L=0.5mH, RG=25ohm

Typical Performance Characteristics

Figure1: Output Characteristics

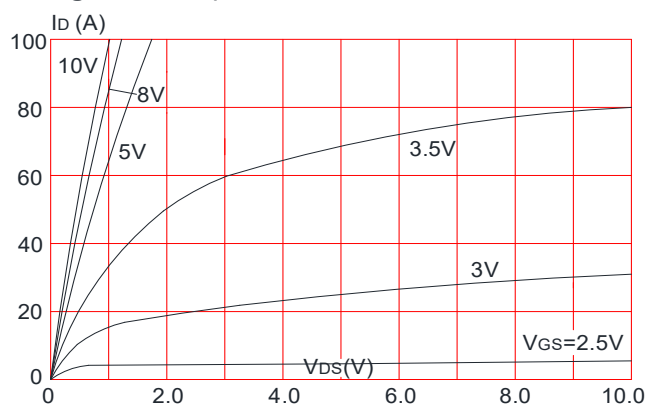


Figure 2: Typical Transfer Characteristics

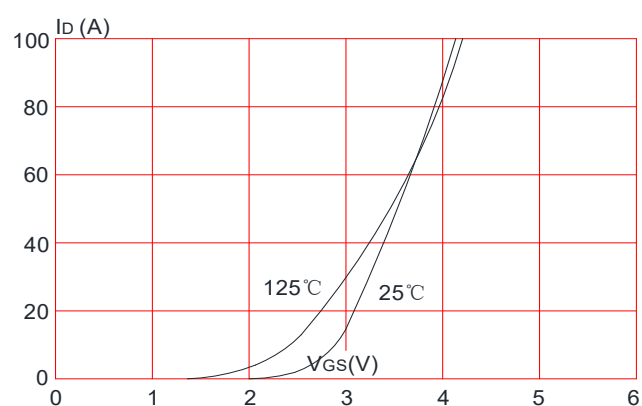


Figure 3: On-resistance vs. Drain Current

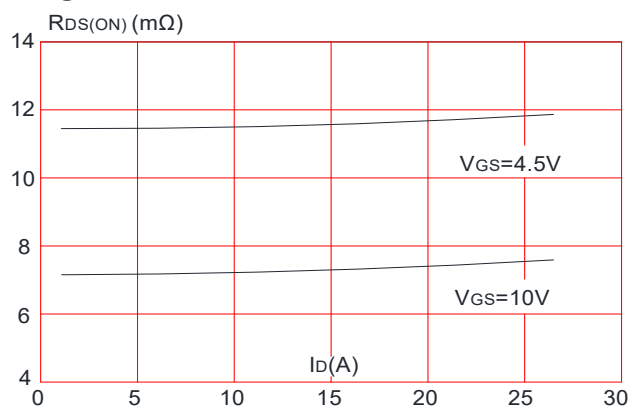


Figure 4: Body Diode Characteristics

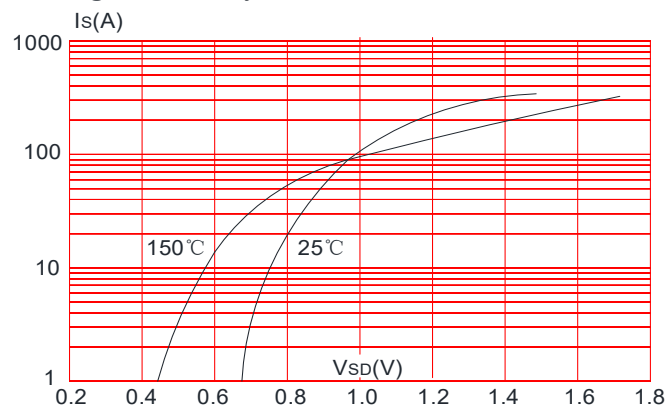


Figure 5: Gate Charge Characteristics

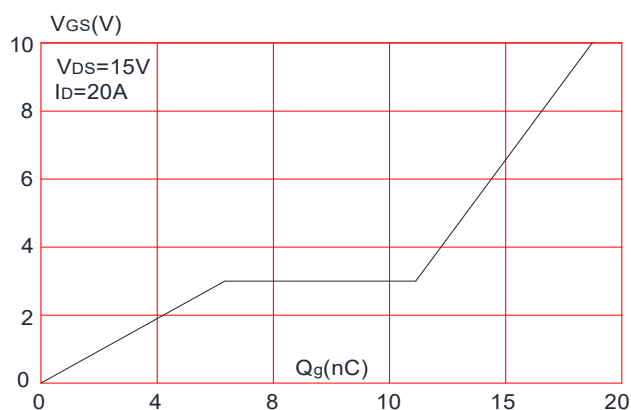


Figure 6: Capacitance Characteristics

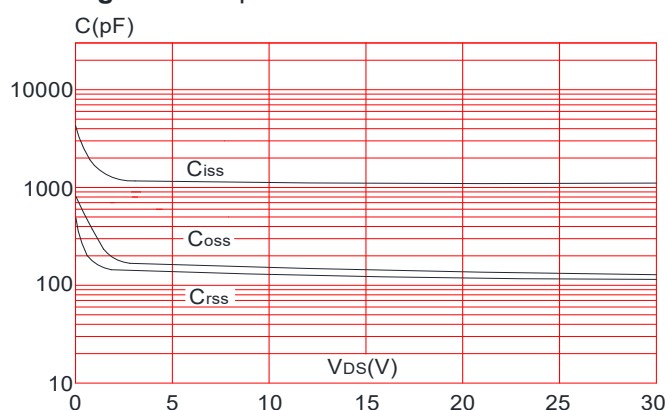


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

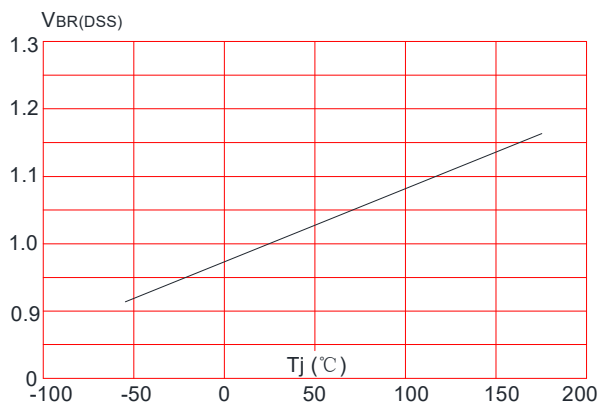


Figure 8: Normalized on Resistance vs. Junction Temperature

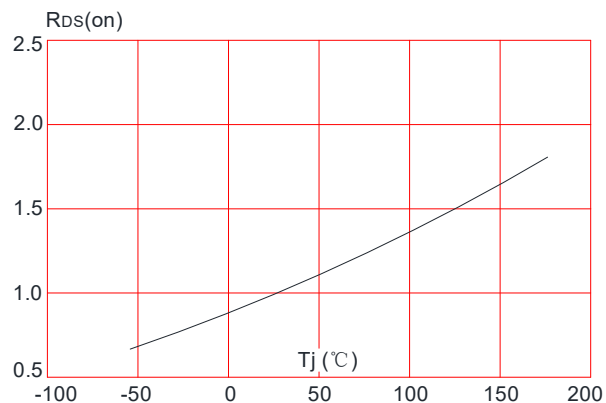
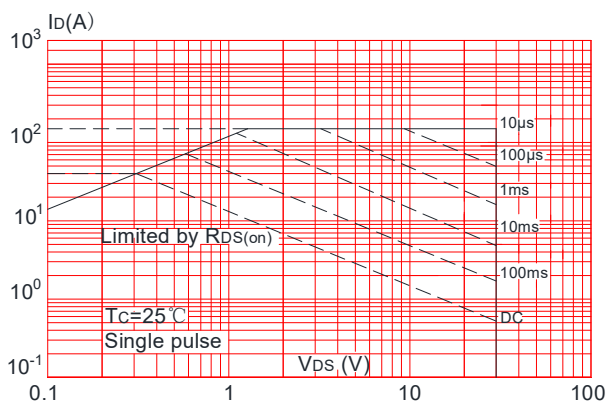


Figure 9: Maximum Safe Operating Area



Maximum Effective Transient Thermal Impedance, Junction-to-Case

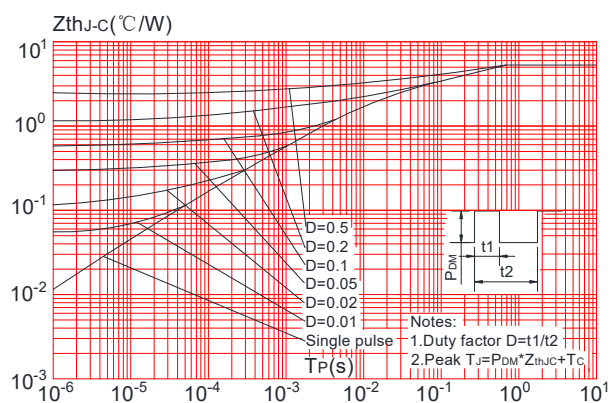
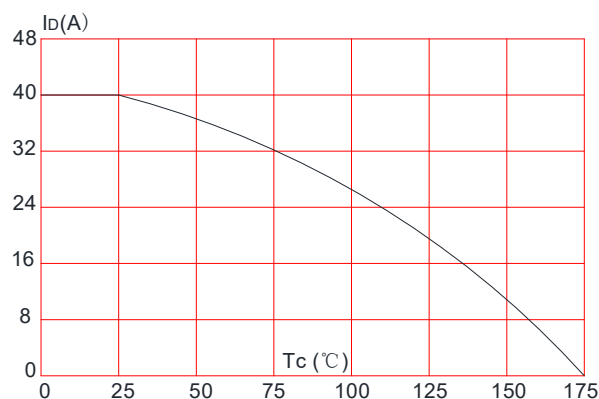


Figure 10: Maximum Continuous Drain Current vs. Case Temperature



Test Circuit

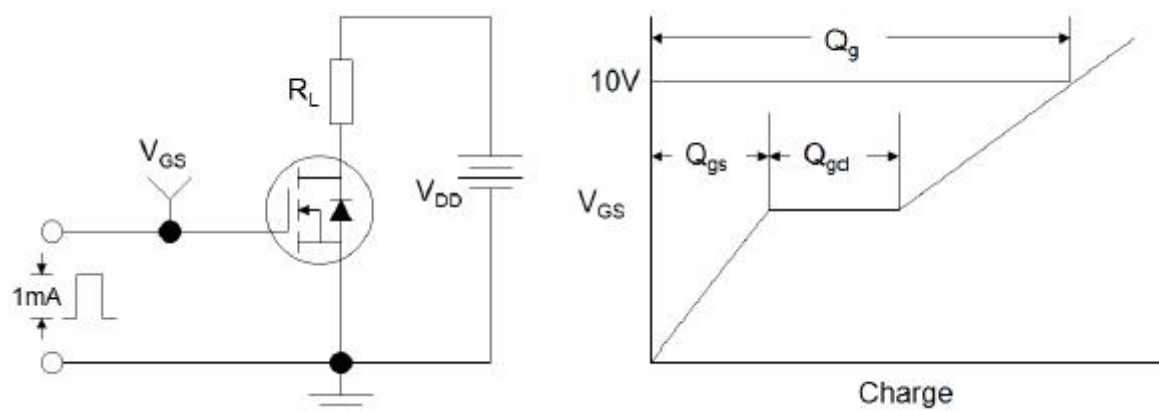


Figure1:Gate Charge Test Circuit & Waveform

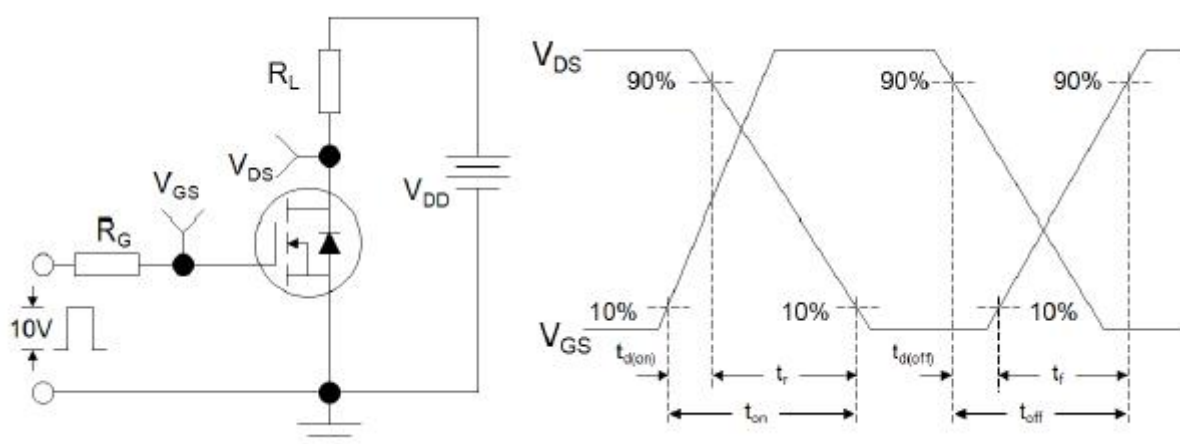


Figure 2: Resistive Switching Test Circuit & Waveforms

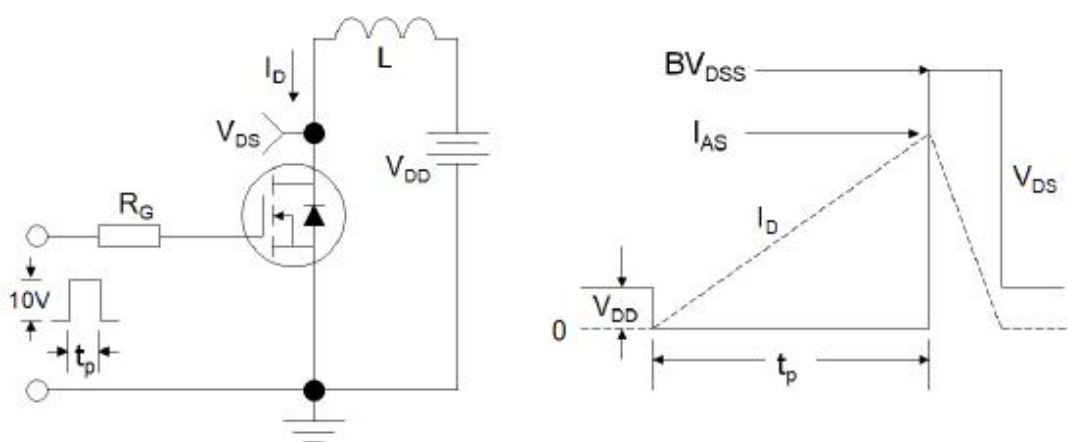
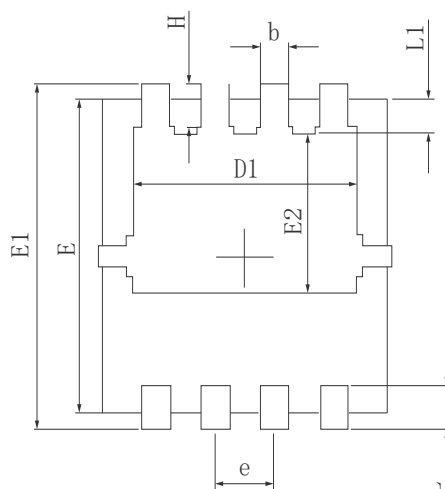
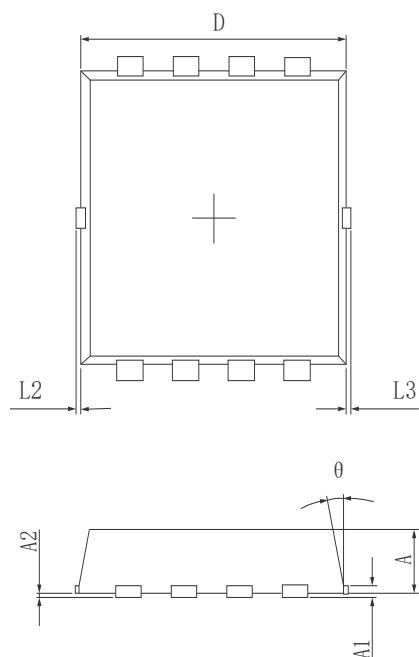
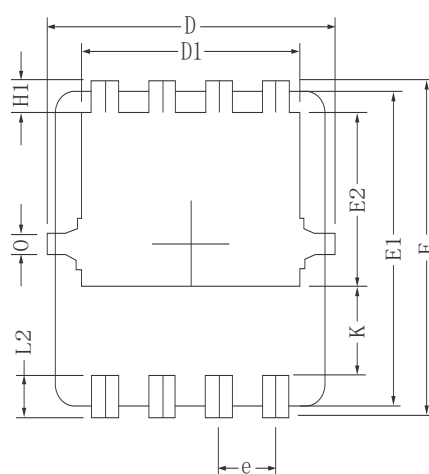
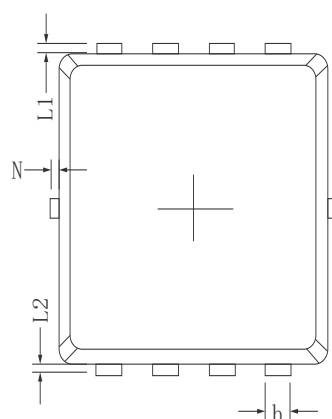


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

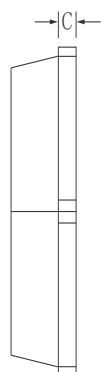
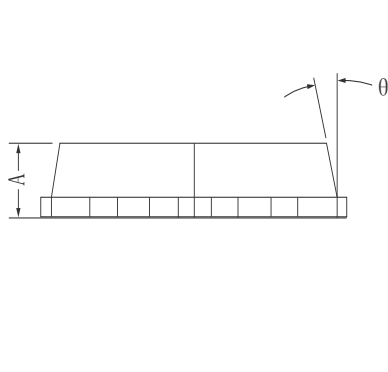
Dimensions (PDFN3.3*3.3)



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	0.700	0.800	0.900
A1	0.152REF.		
A2	0~0.05		
D	3.000	3.100	3.200
D1	2.300	2.450	2.600
E	2.900	3.000	3.100
E1	3.150	3.300	3.450
E2	1.320	1.520	1.720
b	0.200	0.300	0.400
e	0.550	0.650	0.750
L	0.300	0.400	0.500
L1	0.180	0.330	0.480
L2	0~0.100		
L3	0~0.100		
H	0.315	0.415	0.515
θ	8°	10°	12°

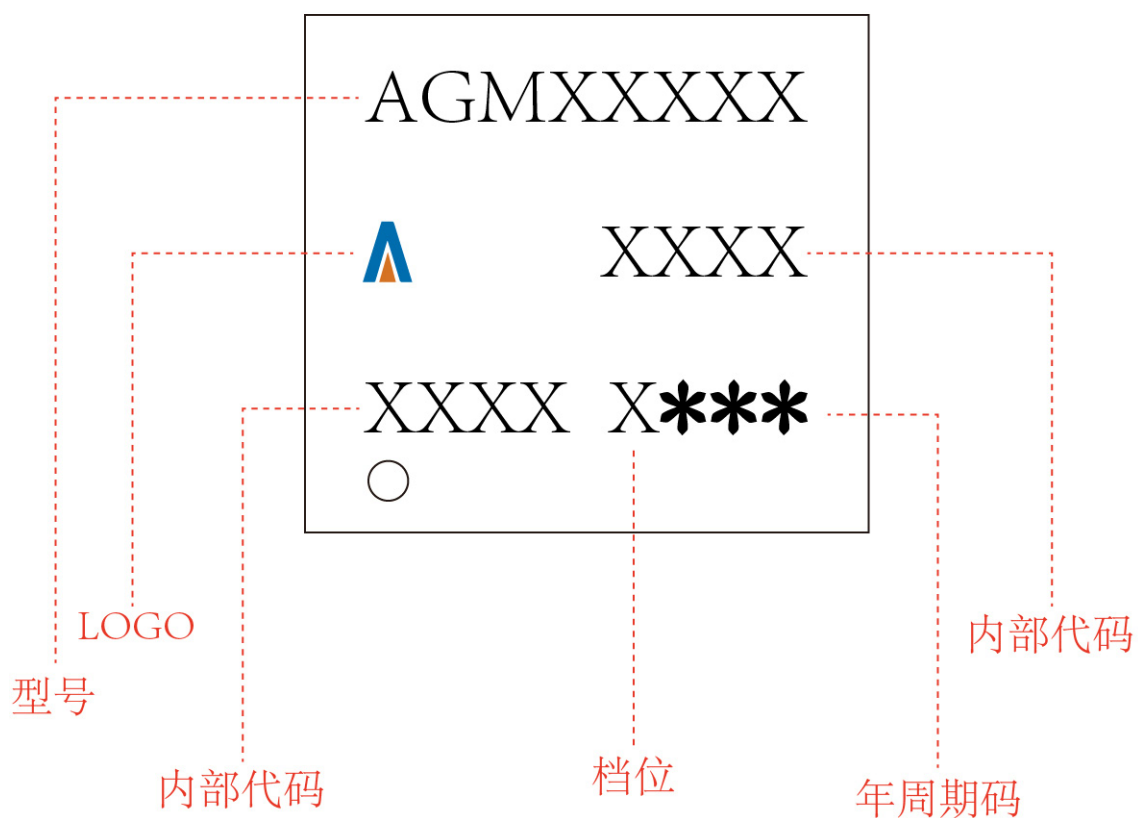


Symbols	Millimeters		
	MIN.	NOM.	MAX.
A	0.65	0.75	0.85
b	0.25	0.30	0.35
C	0.15	0.20	0.25
D	3.00	3.10	3.20
D1	2.40	2.50	2.60
E	3.20	3.30	3.40
E1	3.00	3.10	3.20
E2	1.60	1.70	1.80
e	0.65 BSC.		
H1	0.21	0.31	0.41
H2	0.30	0.40	0.50
K	0.78	0.88	0.98
L1/L2	0.10 REF.		
θ	11°	12°	13°
N	0	-	0.15
O	0.2 REF.		



PDFN3.3*3.3

Marking Instructions:



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